TOSHIBA Power Transistor Module Silicon NPN&PNP Epitaxial Type (Darlington power transistor 6 in 1)

## **MP6301**

# High Power Switching Applications 3-Phase Motor Drive and Bipolar Drive of Pulse Motor

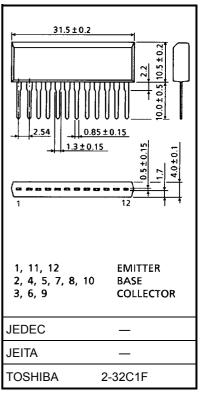
- Small package by full molding (SIP 12 pin)
- High collector power dissipation (6 devices operation)
  - :  $P_T = 4.4 \text{ W (Ta} = 25^{\circ}\text{C)}$
- High collector current:  $I_{C(DC)} = \pm 3 A \text{ (max)}$
- High DC current gain:  $h_{FE} = 2000$  (min) ( $V_{CE} = \pm 2$  V,  $I_{C} = \pm 1$  A)

#### **Maximum Ratings (Ta = 25°C)**

Characteristics		Symbol	Ra	Unit	
		Syllibol	NPN	PNP	Oill
Collector-base voltage		$V_{CBO}$	100	-100	V
Collector-emitter voltage		V <sub>CEO</sub>	80	-80	V
Emitter-base voltage		V <sub>EBO</sub>	8	-8	V
Collector current	DC	IC	3	-3	Α
	Pulse	I <sub>CP</sub>	5	-5	A
Continuous base current		ΙΒ	0.5	-0.5	Α
Collector power dissipation		P <sub>C</sub>	2.0		W
(1 device operation)		FC	2	vv	
Collector power dissipation		P <sub>T</sub>	4	W	
(6 devices operation)		ГΙ	†	VV	
Junction temperature		Tj	150		°C
Storage temperature range		T <sub>stg</sub>	-55 to 150		°C

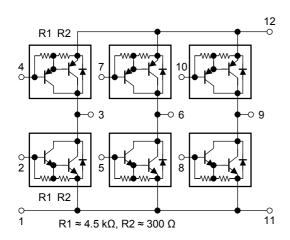
#### **Industrial Applications**

Unit: mm



Weight: 3.9 g (typ.)

### **Array Configuration**





#### **Thermal Characteristics**

Characteristics	Symbol	Max	Unit	
Thermal resistance of junction to ambient	ΣR <sub>th (j-a)</sub>	28.4	°C/W	
(6 devices operation, Ta = 25°C)	,			
Maximum lead temperature for soldering purposes	TL	260	°C	
(3.2 mm from case for 10 s)				

## Electrical Characteristics (Ta = 25°C) (NPN transistor)

Charac	teristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Collector cut-off cu	rrent	I <sub>CBO</sub>	V <sub>CB</sub> = 100 V, I <sub>E</sub> = 0 A	_	_	20	μA
Collector cut-off cu	rrent	I <sub>CEO</sub>	V <sub>CE</sub> = 80 V, I <sub>B</sub> = 0 A	-	-	20	μΑ
Emitter cut-off curre	ent	I <sub>EBO</sub>	V <sub>EB</sub> = 8 V, I <sub>C</sub> = 0 A	0.8	_	4.0	mA
Collector-base brea	akdown voltage	V (BR) CBO	I <sub>C</sub> = 1 mA, I <sub>E</sub> = 0 A	100	_	_	V
Collector-emitter br	eakdown voltage	V (BR) CEO	I <sub>C</sub> = 10 mA, I <sub>B</sub> = 0 A	80	_	_	V
DC aurrent gain		h <sub>FE (1)</sub>	V <sub>CE</sub> = 2 V, I <sub>C</sub> = 1 A	2000	_	_	
DC current gain	h <sub>FE (2)</sub>	V <sub>CE</sub> = 2 V, I <sub>C</sub> = 2 A	1000	_	_	_	
Saturation voltage	Collector-emitter	V <sub>CE (sat)</sub>	I <sub>C</sub> = 2 A, I <sub>B</sub> = 4 mA	_	_	1.8	V
	Base-emitter	V <sub>BE (sat)</sub>	I <sub>C</sub> = 2 mA, I <sub>B</sub> = 4 mA	_	_	2.3	
Transition frequency		f <sub>T</sub>	V <sub>CE</sub> = 2 V, I <sub>C</sub> = 0.5 A	_	100	_	MHz
Collector output capacitance		C <sub>ob</sub>	V <sub>CB</sub> = 10 V, I <sub>E</sub> = 0 A, f = 1 MHz	_	20	_	pF
	Turn-on time	t <sub>on</sub>	Output  Output	_	0.4	_	
	Storage time	t <sub>stg</sub>		ı	3.0	ı	μs
	Fall time	t <sub>f</sub>	$I_{B1} = -I_{B2} = 4 \text{ mA, duty cycle} \le 1\%$	_	0.6	_	

## **Emitter-Collector Diode Ratings and Characteristics (Ta = 25°C)**

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Forward current	I <sub>FM</sub>	_	_	_	3	Α
Surge current	I <sub>FSM</sub>	t = 1 s, 1 shot	_	_	5	Α
Forward voltage	V <sub>F</sub>	I <sub>F</sub> = 1 A, I <sub>B</sub> = 0 A	_	_	2.0	V
Reverse recovery time	t <sub>rr</sub>	I <sub>F</sub> = 3 A, V <sub>BE</sub> = -3 V, dI <sub>F</sub> /dt = -50 A/μs	_	1	_	μs
Reverse recovery charge	Q <sub>rr</sub>			5	_	μC



## **Electrical Characteristics (Ta = 25°C) (PNP transistor)**

Charac	teristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Collector cut-off cu	rrent	I <sub>CBO</sub>	V <sub>CB</sub> = -100 V, I <sub>E</sub> = 0 A	_	_	-20	μΑ
Collector cut-off cu	rrent	I <sub>CEO</sub>	V <sub>CE</sub> = -80 V, I <sub>B</sub> = 0 A	_	_	-20	μΑ
Emitter cut-off curre	ent	I <sub>EBO</sub>	V <sub>EB</sub> = -8 V, I <sub>C</sub> = 0 A	-0.8	_	-4.0	mA
Collector-base brea	akdown voltage	V (BR) CBO	I <sub>C</sub> = -1 mA, I <sub>E</sub> = 0 A	-100	_	_	V
Collector-emitter bi	reakdown voltage	V (BR) CEO	I <sub>C</sub> = -10 mA, I <sub>B</sub> = 0 A	-80	_	_	V
DC surrent gain		h <sub>FE (1)</sub>	V <sub>CE</sub> = -2 V, I <sub>C</sub> = -1 A	2000	_	_	
DC current gain	h <sub>FE (2)</sub>	V <sub>CE</sub> = -2 V, I <sub>C</sub> = -2 A	1000	_	_	_	
0 1 1: 11	Collector-emitter	V <sub>CE (sat)</sub>	I <sub>C</sub> = -2 A, I <sub>B</sub> = -4 mA	_	_	-1.8	V
Saturation voltage	Base-emitter	V <sub>BE (sat)</sub>	I <sub>C</sub> = -2 A, I <sub>B</sub> = -4 mA	_	_	-2.3	
Transition frequency		f <sub>T</sub>	V <sub>CE</sub> = -2 V, I <sub>C</sub> = -0.5 A	_	50	_	MHz
Collector output capacitance		C <sub>ob</sub>	V <sub>CB</sub> = -10 V, I <sub>E</sub> = 0 A, f = 1 MHz	_	30	_	pF
	Turn-on time	t <sub>on</sub>	Output  Input  B2  Output  Vcc = -30 V	_	0.4	_	
	Storage time	t <sub>stg</sub>		l	1.8		μs
	Fall time	t <sub>f</sub>	20 µs -I <sub>B1</sub> = I <sub>B2</sub> = 4 mA, duty cycle ≤ 1%	_	0.4	_	

## **Emitter-Collector Diode Ratings and Characteristics (Ta = 25°C)**

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Forward current	I <sub>FM</sub>	_	_	_	3	Α
Surge current	I <sub>FSM</sub>	t = 1 s, 1 shot	_	_	5	Α
Forward voltage	$V_{F}$	I <sub>F</sub> = 1 A, I <sub>B</sub> = 0 A	_	_	2.0	V
Reverse recovery time	t <sub>rr</sub>	I <sub>F</sub> = 3 A, V <sub>BE</sub> = 3 V, dI <sub>F</sub> /dt = -50 A/μs	_	500	_	μs
Reverse recovery charge	Q <sub>rr</sub>		_	2.7	_	μC

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